



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
* : Required Field			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-01-07
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Floriana San Biagio	Representative Title	AMS MD CHAMPION
Representative Phone *	Refer to Supplier Comment section		Refer to Supplier Comment section
Representative Email *	Refer to Supplier Comment section		
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	KD6R*0324AD6	A	BO2A	2015-01-07
	Amount	UoM	Unit type	ST ECOPACK Grade
	54.82	mg	Each	ECOPACK® 3
	Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	5x4.4x0.9	14	gull wing	
Comment	Package: 6R TSSOP 14 BODY 4.4 PITCH 0.65; MDF valid for LM2902WPT			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	KD6R*0324AD6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	1.760	mg	supplier	die	Silicon (Si)	7440-21-3		1.721	mg	977841	31394
				supplier	metallization	Aluminium (Al)	7429-90-5		0.014	mg	7955	255
				supplier	Passivation	Silicon Nitride	12033-89-5		0.007	mg	3977	128
				supplier	Passivation	Silicon Oxide	7631-86-9		0.009	mg	5114	164
				supplier	glass coating	Glass: Silicon Dioxide	7631-86-9		0.009	mg	5114	164
Leadframe	Copper & its alloys	25.929	mg	supplier	alloy	Copper (Cu)	7440-50-8		24.544	mg	946585	447720
				supplier	alloy	Nickel (Ni)	7440-02-0		0.765	mg	29504	13955
				supplier	alloy	Magnesium (Mg)	7439-95-4		0.038	mg	1466	693
				supplier	alloy	Silicon (Si)	7440-21-3		0.166	mg	6402	3028
				supplier	metallization	Nickel (Ni)	7440-02-0		0.285	mg	10992	5199
				supplier	metallization	Palladium (Pd)	7440-05-3		0.018	mg	694	328
				supplier	metallization	Gold (Au)	7440-57-5		0.008	mg	309	146
				supplier	metallization	Silver (Ag)	7440-22-4		0.105	mg	4050	1915
				supplier	metallization	Silver (Ag)	7440-22-4		0.573	mg	878834	10452
Die attach	Other Organic Materials	0.652	mg	supplier	glue	Isobornyl Methacrylate	7534-94-3		0.033	mg	50613	602
				supplier	glue	Urethane Methacrylate Resin	5888-33-5		0.033	mg	50613	602
				supplier	glue	Acrylate polymer	87320-05-6		0.013	mg	19939	237
				supplier	wire	Copper (Cu)	7440-50-8		0.127	mg	1000000	2317
Encapsulation	Other Organic Materials	26.352	mg	supplier	mold compound	Silica, vitreous	60676-86-0		23.110	mg	876973	421561
				supplier	mold compound	Epoxy resin	85954-11-6		1.054	mg	39997	19227
				supplier	mold compound	Epoxy	29690-82-2		1.054	mg	39997	19227
				supplier	mold compound	phenol resin	Proprietary		0.791	mg	30017	14429
				supplier	mold compound	additive	Proprietary		0.264	mg	10018	4816
				supplier	mold compound	carbon black	1333-86-4		0.079	mg	2998	1441